

PRO'S

could wear
cup 100% Al
cold easily
alt substrate
content

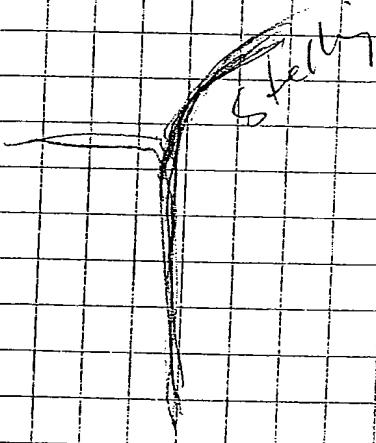
CONS

① needs to
be out of
furnace

a solid as
piece of cake

get your money
worth in \$\$\$

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7/29

∅ order process flow ideas

sin

350 m³

Sac Poly

Poly

50 t

30 s

100

ox

300 t

125

PR

sin

p-17

ox

ph

1. etch nitride CH_4 ,
into poly
2. Cl_2 ~~HBr + BCl_3~~
3. stop on ox
4. SPC undercut
5. NF etch oxide
open Si

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ribbon P.R.

Ribbon P.R.

S:N

Sac poly

P-Si

Via or charge pit
mask

S:N

S:N

M2-poly

oxide

P-Si:

etch stop

step coverage?

extra mask.

contact out of optical area

n
s
s
c

LM1

POST

VIA

M2

M3-field

Rib

Seal

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0. order design

processes
to PnA identical metal legs just prior

Si:N

poly

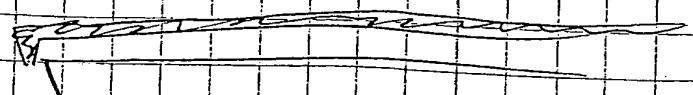
Si:N

poly

ribbon mask + etch
short release

maybe add via mask + etch
at over

poly



glass

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